



SLOVENSKI STANDARD
kSIST FprEN 16602-70-38:2018
01-september-2018

Zagotavljanje kakovosti proizvodov v vesoljski tehniki - Visoka zanesljivost spajkanja za površinsko montažo in mešano tehnologijo

Space product assurance - High-reliability soldering for surface-mount and mixed technology

Raumfahrtproduktsicherung - Hochzuverlässiges Löten von Oberflächen-Befestigungen und gemischte Technologien

Assurance produit spatiale - Soudure haute fiabilité pour technologies à montage de surface et mixte

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Ta slovenski standard je istoveten z: FprEN 16602-70-38

ICS:

25.160.50	Trdo in mehko lotanje	Brazing and soldering
49.140	Vesoljski sistemi in operacije	Space systems and operations

kSIST FprEN 16602-70-38:2018

en,fr,de

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

FINAL DRAFT
FprEN 16602-70-38

June 2018

ICS 25.160.50; 49.140

English version

Space product assurance - High-reliability soldering for surface-mount and mixed technology

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pour technologies à montage de surface et mixte

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Löten von Oberflächen-Befestigungen und gemischte
Technologien

This draft European Standard is submitted to CEN members for unique acceptance procedure. It has been drawn up by the Technical Committee CEN/CLC/JTC 5.

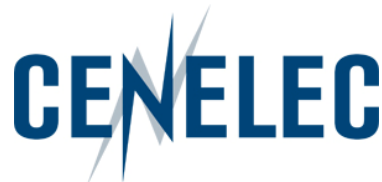
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Table of contents

European Foreword	11
Introduction	12
1 Scope	15
2 Normative references	16
3 Terms, definitions and abbreviated terms	18
3.1 Terms from other standards.....	18
3.2 Terms specific to the present standard	18
3.3 Abbreviated terms.....	20
3.4 Nomenclature	21
3.4.1 Formal verbs	21
4 Principles of reliable soldered connections	22
5 Process identification document (PID)	23
5.1 General.....	23
5.1.1 Purpose	23
5.1.2 Document preparation.....	23
5.1.3 <<deleted>>	23
5.1.4 Approval.....	23
5.1.5 SMT contact person	24
5.2 <<deleted>>	24
5.3 Process identification document updating	24
6 Preparatory conditions	25
6.1 Calibration	25
6.2 Facility cleanliness.....	25
6.3 Environmental conditions.....	25
6.4 Precautions against static charges	25
6.5 Lighting requirements	25
6.6 Equipment and tools	25
6.6.1 Brushes.....	25

6.6.2	Cutters and Pliers	26
6.6.3	Bending tools	26
6.6.4	Clinching tools.....	26
6.6.5	Insulation strippers	26
6.6.6	Soldering tools	26
6.6.7	Soldering irons and resistance soldering equipment	26
6.6.8	<<deleted>>.....	26
6.6.9	Solder baths for degolding and pretinning	26
6.7	Soldering machines and equipment.....	27
6.7.1	General.....	27
6.7.2	Dynamic wave-solder machines.....	27
6.7.3	Condensation (vapour phase) reflow machines.....	28
6.7.4	Hot gas reflow machines.....	28
6.7.5	<<deleted>>.....	28
6.7.6	Convection and radiation reflow systems	28
6.7.7	Other equipment for reflow soldering	29
6.8	Ancillary equipment	29
6.8.1	General.....	29
6.8.2	Solder deposition equipment.....	29
6.8.3	Automatic device placement equipment.....	29
6.8.4	<<deleted>>.....	29
6.8.5	Cleanliness testing equipment	30
6.8.6	Magnification aids	30
6.8.7	X-ray inspection equipment.....	30
6.8.8	Metallographic equipment	30
7	Material selection	31
7.1	General.....	31
7.2	Solder	31
7.2.1	Form	31
7.2.2	Composition.....	31
7.2.3	Solder paste.....	31
7.2.4	Maintenance of paste purity	33
7.3	Flux	33
7.3.1	Rosin based flux	33
7.3.2	Corrosive acid flux.....	33
7.3.3	Flux controls for wave-soldering equipment	33
7.4	Solvents.....	33

FprEN 16602-70-38:2018 (E)

7.5	Flexible insulation materials.....	34
7.6	Terminals.....	34
7.7	Wires.....	34
7.8	Printed circuit substrates.....	34
7.8.1	<<deleted>>.....	34
7.8.2	<<deleted>>.....	34
7.8.3	<<deleted>>.....	34
7.8.4	<<deleted>>.....	34
7.8.5	<<deleted>>.....	35
7.8.6	<<deleted>>.....	35
7.9	Devices.....	35
7.9.1	General.....	35
7.9.2	<<deleted>>.....	36
7.9.3	Moisture sensitive devices.....	36
7.9.4	<<deleted>>.....	36
7.10	Adhesives, encapsulants and conformal coatings.....	36
8	Preparation for soldering.....	38
8.1	Preparation of devices and terminals.....	38
8.1.1	Preparation of wires and terminals.....	38
8.1.2	Preparation of surfaces to be soldered.....	38
8.1.3	Degolding and pretinning of conductors.....	38
8.1.4	Alloying of pure tin finish.....	38
8.2	Preparation of solder bit.....	39
8.3	Handling.....	39
8.4	Storage.....	39
8.5	Baking of PCBs and moisture sensitive devices.....	39
9	Mounting of devices prior to soldering.....	40
9.1	General requirements.....	40
9.2	Lead bending and cutting requirements.....	40
9.3	Mounting of terminals to PCBs.....	40
9.4	Lead attachment to through holes.....	40
9.5	Mounting of devices to terminals.....	40
9.6	Mounting of through hole connectors to PCBs.....	40
9.7	Surface mount requirements.....	41
9.7.1	General.....	41
9.7.2	Stress relief.....	41
9.7.3	Registration of devices and footprints.....	42

9.7.4	Lead forming	42
9.7.5	Mounting devices in solder paste	42
9.7.6	Leadless devices	43
9.7.7	Leaded devices	43
9.7.8	<<deleted>>	43
9.7.9	Stacking and bonding of heavy devices	43
10	Attachment of conductors to terminals, solder cups and cables	45
11	Soldering to printed circuit boards	46
11.1	General.....	46
11.2	<<deleted>>	46
11.3	Solder applications to PCBs	46
11.4	Wicking.....	46
11.5	Soldering of SMDs.....	46
11.5.1	General requirements	46
11.5.2	End-capped and end-metallized devices.....	47
11.5.3	Bottom terminated chip devices	49
11.5.4	Cylindrical and square end-capped devices	50
11.5.5	Castellated chip carrier devices.....	52
11.5.6	Flat pack and Gull-wing leaded devices with round, rectangular, ribbon leads	53
11.5.7	Devices with "J" leads	54
11.5.8	Area array devices	54
11.5.9	Devices with ribbon terminals without stress relief	56
11.5.10	L-Shape inwards devices	57
11.5.11	Stacked modules devices with leads protruding vertically from bottom.....	58
11.5.12	Leaded device with plane termination	59
11.5.13	Moulded magnetics	59
11.6	<<deleted>>	60
11.7	<<deleted>>	60
11.8	<<deleted>>	60
12	Cleaning of PCB assemblies	61
12.1	General.....	61
12.2	Ultrasonic cleaning	61
12.3	Monitoring for cleanliness	61
13	Final inspection	62
13.1	General.....	62

FprEN 16602-70-38:2018 (E)

13.2	Acceptance criteria	62
13.3	Visual rejection criteria.....	63
13.4	X-ray rejection criterion	65
13.5	Warp and twist of populated boards.....	65
13.6	Inspection records	65
14	Verification procedure.....	66
14.1	General.....	66
14.2	Verification by similarity	68
14.2.1	General	68
14.2.2	Conditions for similarity	69
14.3	Verification programme.....	71
14.4	Electrical testing of devices.....	75
14.4.1	General	75
14.5	Vibration and shock	78
14.6	Temperature cycling test.....	78
14.7	Microsection	79
14.7.1	Microsection facilities	79
14.7.2	Microsectioning	79
14.8	<<deleted>>	95
14.9	Special verification testing for hermetic ceramic area array packages	95
14.9.1	<<deleted>>	95
14.9.2	<<deleted>>	95
14.9.3	General	95
14.9.4	Evaluation of capability samples	98
14.9.5	Verification	98
14.10	Verification acceptance and rejection criteria	99
14.11	Approval of verification	108
14.12	Withdrawal of approval status.....	108
14.13	Conditions for delta verification	108
14.14	Verification of cleanliness	111
14.15	Verification approval procedure	111
14.15.1	Request for verification	111
14.15.2	Technology sample.....	111
14.15.3	Audit of assembly processing.....	111
14.15.4	Verification programme	112
14.15.5	Final verification review.....	112
14.15.6	Certification approval of assembly line	112

15 Quality assurance	113
15.1 General.....	113
15.2 Data.....	113
15.3 Nonconformance	113
15.4 Calibration	113
15.5 Traceability	113
15.6 Workmanship standards	113
15.7 Inspection	114
15.8 Operator and inspector training and certification.....	114
15.9 Quality records	114
16 <<deleted and moved into clause 14.7.2 and Annex I>>	115
Annex A (informative) <<deleted>>	116
Annex B (informative) <<deleted, SMT summary table DRD created in Annex H>>	117
Annex C (informative) <<deleted>>	118
Annex D (informative) Example of an SMT audit report	119
Annex E (informative) Additional information	128
E.1 <<deleted>>	128
E.2 Melting temperatures and choice.....	128
Annex F (normative) Process Identification Document (PID) - DRD	129
F.1 DRD identification.....	129
F.1.1 Requirement identification and source document.....	129
F.1.2 Purpose and objective.....	129
F.2 Expected response	129
F.2.1 Scope and content.....	129
F.2.2 Special remarks	131
Annex G (normative) Verification programme report - DRD	132
G.1 DRD identification.....	132
G.1.1 Requirement identification and source document.....	132
G.1.2 Purpose and objective.....	132
G.2 Expected response.....	132
G.2.1 Scope and content.....	132
G.2.2 Special remarks	133
Annex H (normative) SMT summary table - DRD	134

FprEN 16602-70-38:2018 (E)

H.1	DRD identification.....	134
H.1.1	Requirement identification and source document.....	134
H.1.2	Purpose and objective.....	134
H.2	Expected response.....	134
H.2.1	Scope and content.....	134
H.2.2	Special remarks.....	134
Annex I (informative) Visual and X-ray workmanship standards		136
I.1	Workmanship illustrations for standard SMDs.....	136
I.1.1	Chip components.....	136
I.1.2	MELF components.....	139
I.1.3	Gull-wing leaded devices with round, rectangular, ribbon shape.....	140
I.1.4	“J” leaded devices.....	142
I.1.5	L-shape Inward leaded component.....	144
I.1.6	LCC devices.....	144
I.1.7	Miscellaneous soldering defects.....	145
I.2	Workmanship illustrations for ball grid array devices.....	146
I.3	Workmanship illustrations for column grid array devices.....	148
Bibliography.....		151
Figures		
Figure 9-1:	Exposed element.....	43
Figure 11-1:	Mounting of rectangular and square end-capped and end-metallized devices.....	48
Figure 11-2:	Mounting of bottom terminated chip devices.....	49
Figure 11-3:	Mounting of cylindrical end-capped devices.....	50
Figure 11-4:	Mounting of square end-capped devices.....	51
Figure 11-5:	Mounting of castellated chip carrier devices.....	52
Figure 11-6:	Mounting of gull-wing leaded devices with round, rectangular, ribbon leads.....	53
Figure 11-7:	Mounting of devices with “J” leads.....	54
Figure 11-8:	<<deleted>>.....	55
Figure 11-9:	Typical ceramic area array showing ball grid array configuration on left and column grid array on right (CBGA & CCGA).....	55
Figure 11-10:	Typical assembled CCGA device.....	55
Figure 11-11:	Mounting of devices without stress relief.....	56
Figure 11-12:	Mounting of devices with “L-shape inwards” leads (1 = Toe, 2 = Heel).....	57
Figure 11-13:	Mounting of stacked modules devices with leads protruding vertically from bottom.....	58

Figure 11-14: Mounting of leaded devices with leads with plane termination59

Figure 11-15: <<deleted>> 60

Figure 14-1: Verification programme flow chart (standard flow) 74

Figure 14-2: Verification programme flow chart (electrical testing)..... 77

Figure 14-3: Verification programme flow chart (AAD)..... 97

Figure 14-4: <<deleted>> 100

Figure I-1 : Preferred solder (see also Table 11-1) 136

Figure I-2 : Acceptable, maximum solder (see also Table 11-1) 136

Figure I-3 : Acceptable, minimum Solder (see also Table 11-1)..... 137

Figure I-4 : Unacceptable, excessive solder (see also Table 11-1)..... 137

Figure I-5 : Unacceptable, poor wetting (see also Table 11-1)..... 137

Figure I-6 : Unacceptable, excessive tilt (see also Table 11-1)..... 138

Figure I-7 : Unacceptable, tombstone effect 138

Figure I-8 : Examples of Unacceptable solder joints - (see also Table 11-1)..... 138

Figure I-9 : Acceptable, terminal wetted along end, face and sides (see also Table 11-1)..... 139

Figure I-10 : Acceptable, maximum solder joint (see also Table 11-3)..... 139

Figure I-11 : Not Acceptable, insufficient solder joint (see also Table 11-3)..... 139

Figure I-12 : Unacceptable overhang..... 139

Figure I-13 : Examples of Gullwing leads: Acceptable 140

Figure I-14 : Examples of gull-wing device with rectangular lead: Acceptable 140

Figure I-15 : Acceptable, minimum solder joint 140

Figure I-16 : Unacceptable, insufficient heel fillet..... 141

Figure I-17 : Unacceptable, excessive solder 141

Figure I-18 : Unacceptable, excessive solder 141

Figure I-19 : Preferred solder joint 142

Figure I-20 : Acceptable solder joint 142

Figure I-21 : Unacceptable, excessive solder joint..... 143

Figure I-22 : Unacceptable, excessive degolding..... 143

Figure I-23 : Acceptable, preferred solder joint 144

Figure I-24 : LCC General view, acceptable solder joints 144

Figure I-25 : Examples of unacceptable soldering 145

Figure I-26 : Angled-transmission X-radiograph showing solder paste shadow due to partial reflow: Reject..... 146

Figure I-27 : Micrograph showing 146

Figure I-28 : Perpendicular transmission X-radiograph showing unacceptable defects..... 147

Figure I-29 : Perpendicular transmission X-radiograph showing non-wetted footprint..... 147

Figure I-30 : Underside view showing missing column..... 148

Figure I-31 : CGA mounted on PCB showing columns tilted < 10°: Accept..... 148

FprEN 16602-70-38:2018 (E)

Figure I-32 : X-radiograph of CGA mounted on PCB showing solder bridge: Reject.....	149
Figure I-33 : X-radiograph of CGA showing solder fillets at base of columns: acceptable ...	149
Figure I-34 : Micrograph of CGA mounted on PCB, bent column: reject	150
Figure I-35 : Micrograph of CGA mounted on PCB.....	150

Tables

Table 7-1: Chemical composition of spacecraft solders	32
Table 7-2: <<deleted>>	34
Table 11-1: Dimensional and solder fillet for rectangular and square end capped devices	48
Table 11-2: Dimensional and solder fillet for bottom terminated chip devices	49
Table 11-3: Dimensional and solder fillet for cylindrical end-capped devices.....	50
Table 11-4: Dimensional and solder fillet for square end-capped devices	51
Table 11-5: Dimensional and solder fillet for castellated chip carrier devices.....	52
Table 11-6: Dimensional and solder fillet for gull-wing leaded devices with round, rectangular, ribbon leads	53
Table 11-7: Dimensional and solder fillet for devices with “J” leads	54
Table 11-8: Dimensional and solder fillet for area array devices	55
Table 11-9: Dimensional and solder fillet for devices without stress relief.....	56
Table 11-10: Dimensional and solder fillet for “L-shape inwards” devices.....	57
Table 11-11: Dimensional and solder fillet for stacked modules devices with leads protruding vertically from bottom	58
Table 11-12: Dimensional and solder fillet for leaded devices with plane termination	59
Table 14-1: Device type classification.....	68
Table 14-2: Device microsection location	81
Table 14-3: Critical zone definition per device type and acceptance criteria	101
Table 14-4: Conditions invoking verification.....	110
Table E-1 : Guide for choice of solder type.....	128
Table H-1 : Device type preparation and mounting configuration.....	135

European Foreword

This document (FprEN 16602-70-38:2018) has been prepared by Technical Committee CEN/CLC/TC 5 "Space", the secretariat of which is held by DIN (Germany).

This document (FprEN 16602-70-38:2018) originates from ECSS-Q-ST-70-38C Rev.1.

This document is currently submitted to the Unique Acceptance Procedure.

This document has been developed to cover specifically space systems and will therefore have precedence over any EN covering the same scope but with a wider domain of applicability (e.g.: aerospace).

This document has been prepared under a mandate given to CEN by the European Commission and the European Free Trade Association.

STANDARD PREVIEW
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SIST EN 16602-70-38:2019

<https://standards.iteh.ai/catalog/standards/sist/3201eb07-6f03-4bb4-be09-fbce25c8b627/sist-en-16602-70-38-2019>

Introduction

This Standard prescribes requirements for electrical connections of leadless and leaded surface mounted devices (SMD) on spacecraft and associated equipment, utilising a range of substrate assemblies and employing solder as the interconnection media. The principal types of SMDs can be gathered in the following families:

<p>Rectangular and square end-capped or end-metallized device with rectangular body, leadless chip (see 11.5.2) e.g. end capped chip resistors and end capped chip capacitors.</p>	
<p>Cylindrical and square end-capped devices with cylindrical body, leadless chip (see 11.5.4) e.g. MELF for cylindrical end capped or e.g. D-5A for square end capped</p>	
<p>Bottom terminated chip device (see 11.5.3) This type of device has metallised terminations on the bottom side only. e.g. inductors and SMD0.5, SMD1, SMD2, SMD0.2, SMD0.22 e.g. Quad Flat Pack No lead (QFN)</p>	

<p>Castellated chip carrier device (see 11.5.5)</p> <p>The main device of this type is leadless ceramic chip carrier (LCCC).</p> <p>e.g. LCC6</p>	
<p>Flat pack and gull-wing leaded device with round, rectangular, ribbon leads (see 11.5.6)</p> <p>e.g. small-outline transistor (SOT), small-outline package (SO), flat pack and quad flat pack (QFP) and SMD connectors with stress-relief.</p> <p>This family also comprises devices for through-hole mounting that have been reconfigured to surface mounting.</p>	
<p>Moulded magnetics (see 11.5.13)</p> <p>e.g. 1553 interface transformers or specific transformers</p> <p><i>iTeh STANDARD PREVIEW (standards.iteh.ai)</i></p> <p><i>SIST EN 16602-70-38:2019</i></p> <p><i>https://standards.iteh.ai/catalog/standards/sist/32016b07-6f03-4140-9000-fbce25c8b627/sist-en-16602-70-38-2019</i></p>	
<p>“J” leaded device (see 11.5.7)</p> <p>e.g. ceramic leaded chip carriers (CLCC) and plastic leaded chip carriers (PLCC).</p>	